

**Photodetector, especially a photodiode array useful for optical data storage and transmission, image processing, pattern recognition and spectrometry, is produced by back face bonding of a thinned photodetector wafer to a contact substrate**

**Publication number:** DE19838442  
**Publication date:** 2000-03-02  
**Inventor:** BUCHNER REINHOLD (DE); SAX MELANIE (DE)  
**Applicant:** FRAUNHOFER GES FORSCHUNG (DE)  
**Classification:**  
- **international:** H01L27/146; H01L27/146; (IPC1-7): H01L27/146  
- **european:** H01L27/146A  
**Application number:** DE19981038442 19980824  
**Priority number(s):** DE19981038442 19980824

**Report a data error here**

## Abstract of DE19838442

A photodetector production process, comprising back face bonding of a supported thinned photodetector wafer to a contact substrate having conductor lines and connection pads, is new. A photodetector production process comprises: (a) producing a substrate wafer (1) with a photosensitive region between two laterally spaced conductive regions (4, 5) on its front face; (b) bonding the wafer front face to an auxiliary support; (c) thinning the wafer back face down to (near) the conductive regions; (d) preparing a contact substrate having one or more contacting levels with conductor lines and connection areas for contacting the conductive regions (4, 5); (e) bonding the thinned wafer back face to the contact substrate such that the conductive regions lie above the connection areas; (f) removing the auxiliary support; and (g) producing electrical connections between the connection areas and the conductive regions.

Data supplied from the ***esp@cenet*** database - Worldwide